SCAS304D - MARCH 1993 - REVISED JUNE 1997

 EPIC[™] (Enhanced-Performance Implanted CMOS) Submicron Process 	DB, DW, OR PW PACKAGE (TOP VIEW)			
 Typical V_{OLP} (Output Ground Bounce) < 0.8 V at V_{CC} = 3.3 V, T_A = 25°C 	$ \overline{OE} \begin{bmatrix} 1 & 24 \end{bmatrix} V_{CC} $ $ 1D \begin{bmatrix} 2 & 23 \end{bmatrix} 1Q $			
• Typical V _{OHV} (Output V _{OH} Undershoot)	2D 3 22 2Q			
> 2 V at V _{CC} = 3.3 V, T _A = 25°C	3D 4 21 2 3Q			
 Supports Mixed-Mode Signal Operation on 	4D 🛛 5 20 🗍 4Q			
All Ports (5-V Input/Output Voltage With	5D 🛛 6 19 🗍 5Q			
3.3-V V _{CC})	6D 🛛 7 18 🗍 6Q			
 Power Off Disables Inputs/Outputs, 	7D [8 17] 7Q			
Permitting Live Insertion	8D 🛛 9 16 🗍 8Q			
 ESD Protection Exceeds 2000 V Per 	9D 🚺 10 15 🗍 9Q			
MIL-STD-883, Method 3015	10D 🛛 11 14 🗋 10Q			
 Latch-Up Performance Exceeds 250 mA Per JESD 17 	GND [12 13] CLK			

 Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages

description

This 10-bit bus-interface flip-flop is designed for 2.7-V to 3.6-V V_{CC} operation.

The SN74LVC821A features 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing wider buffer registers, I/O ports, bidirectional bus drivers with parity, and working registers.

The ten flip-flops are edge-triggered D-type flip-flops. On the positive transition of the clock (CLK) input, the device provides true data at the Q outputs.

A buffered output-enable (\overline{OE}) input can be used to place the ten outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without interface or pullup components.

OE does not affect the internal operations of the latch. Previously stored data can be retained or new data can be entered while the outputs are in the high-impedance state.

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of these devices as translators in a mixed 3.3-V/5-V system environment.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74LVC821A is characterized for operation from -40°C to 85°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

EPIC is a trademark of Texas Instruments Incorporated.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



Copyright © 1997, Texas Instruments Incorporated

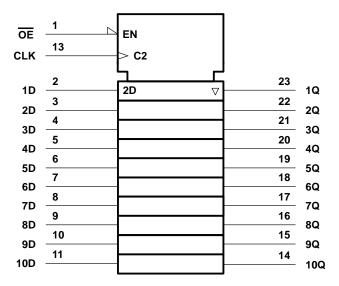
1

SCAS304D - MARCH 1993 - REVISED JUNE 1997

FUNCTION TABLE

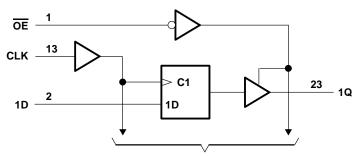
(each flip-flop)							
INPUTS			OUTPUT				
OE	CLK	D	Q				
L	\uparrow	Н	Н				
L	\uparrow	L	L				
L	H or L	Х	Q ₀				
Н	Х	Х	Z				

logic symbol[†]



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



To Nine Other Channels



SCAS304D - MARCH 1993 - REVISED JUNE 1997

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC} Input voltage range, V_I (see Note 1) Voltage range applied to any output in the high-impedance or power-off state, V_O	$\ldots \ldots -0.5$ V to 6.5 V
(see Note 1)	
Voltage range applied to any output in the high or low state, V_{O}	
(see Notes 1 and 2)	\dots –0.5 V to V _{CC} + 0.5 V
Input clamp current, I _{IK} (V _I < 0)	–50 mA
Output clamp current, I_{OK} (V _O < 0 or V _O > V _{CC})	±50 mA
Continuous output current, $I_O (V_O = 0 \text{ to } V_{CC})$ (see Note 2)	±50 mA
Continuous current through V _{CC} or GND	±100 mA
Package thermal impedance, θ_{JA} (see Note 3): DB package	104°C/W
DW package	81°C/W
PW package	120°C/W
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The value of V_{CC} is provided in the recommended operating conditions table.

3. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 4)

			MIN	MAX	UNIT	
Vee	Opera	Operating	2	3.6	V	
Vcc	Supply voltage	Data retention only	1.5		v	
VIH	High-level input voltage	V_{CC} = 2.7 V to 3.6 V	2		V	
VIL	Low-level input voltage	V_{CC} = 2.7 V to 3.6 V		0.8	V	
VI	Input voltage		0	5.5	V	
Va	Output voltage	High or low state	0	VCC	V	
Vo		3 state	0	5.5	v	
1	V _{CC} =	V _{CC} = 2.7 V		-12	mA	
ЮН	High-level output current	$V_{CC} = 3 V$		-24	ША	
1.0.		$V_{CC} = 2.7 V$		12		
IOL	Low-level output current V _{CC} = 3 V			24	mA	
$\Delta t / \Delta v$	Δv Input transition rise or fall rate			10	ns/V	
ТА	T _A Operating free-air temperature			85	°C	

NOTE 4: Unused inputs must be held high or low to prevent them from floating.



SCAS304D - MARCH 1993 - REVISED JUNE 1997

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARA	AMETER	TEST CO	V _{CC}	MIN	түр†	MAX	UNIT		
		I _{OH} = −100 μA		2.7 V to 3.6 V	V _{CC} -0.2				
Mari		10 m A			2.2			v	
Vон		I _{OH} = -12 mA		3 V	2.4			v	
		I _{OH} = -24 mA		3 V	2.2				
		I _{OL} = 100 μA		2.7 V to 3.6 V			0.2		
VOL		I _{OL} = 12 mA		2.7 V			0.4	V	
		I _{OL} = 24 mA		3 V			0.55		
l		V _I = 0 to 5.5 V		3.6 V			±5	μA	
loff		$V_{I} \text{ or } V_{O} = 5.5 \text{ V}$		0			±10	μA	
IOZ		$V_{O} = 0$ to 5.5 V		3.6 V			±10	μA	
lcc		$V_{I} = V_{CC} \text{ or } GND$		3.6 V			10		
		$3.6 \text{ V} \le \text{V}_{\text{I}} \le 5.5 \text{ V}^{\ddagger}$	IO = 0	3.6 V	10		μA		
∆lCC		One input at V _{CC} – 0.6 V,	Other inputs at V_{CC} or GND	2.7 V to 3.6 V			500	μA	
Ci	Control	V _I = V _{CC} or GND		3.3 ∨		5		ъĒ	
	Data			5.5 V		4		pF	
Co	C_0 $V_0 = V_{CC} \text{ or GND}$		3.3 V		7		pF		

[†] All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

[‡] This applies in the disabled state only.

timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

		V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 2.7 V		UNIT
		MIN	MAX	MIN	MAX	
fclock	Clock frequency	0	150	0	150	MHz
tw	Pulse duration, CLK high or low	3.3		3.3		ns
t _{su}	Setup time, data before CLK	1.9		1.9		ns
th	Hold time, data after CLK	1.5		1.5		ns

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	PARAMETER	FROM (INPUT)	ТО (OUTPUT)	V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 2.7 V		UNIT
			MIN	MAX	MIN	MAX		
f _{max}			150		150		MHz	
^t pd	CLK	Q	2.2	7.3		8.5	ns	
ten	OE	Q	1.3	7.6		8.8	ns	
^t dis	OE	Q	1.6	6.2		6.8	ns	
t _{sk(o)} §				1			ns	

§ Skew between any two outputs of the same package switching in the same direction. This parameter is warranted but not production tested.



TEST CONDITIONS

SCAS304D - MARCH 1993 - REVISED JUNE 1997

ТҮР

65

UNIT

Outputs enabled Cpd Power dissipation capacitance per latch $C_{I} = 0 pF$, f = 10 MHzpF 48 Outputs disabled PARAMETER MEASUREMENT INFORMATION 0 6 V TEST **S1** O Open **500** Ω From Output Open ^tpd \sim **Under Test** O GND 6 V tPLZ/tPZL GND tPHZ/tPZH $C_I = 50 \text{ pF}$ **500** Ω (see Note A) 2.7 V LOAD CIRCUIT 1.5 V **Timing Input** 0 V t_w t_{su} th 2.7 V 2.7 V 1.5 V 1.5 V Input 1.5 V 1.5 V Data Input 0 V 0 V **VOLTAGE WAVEFORMS VOLTAGE WAVEFORMS** PULSE DURATION SETUP AND HOLD TIMES 2.7 V 2.7 V Output 1.5 V 1.5 V 1.5 V 1.5 V Input Control 0 V 0 V ^tPZL -^tPHL ^tPLH ^tPLZ Output - V_{OH} 3 V Waveform 1 1.5 V 1.5 V 1.5 V V<u>oL + 0.3 V</u> VoL Output S1 at 6 V VOL (see Note B) ^tPHZ ^tPLH tPHL tPZH -Output VOH ۷он V_{OH} - 0.3 V Waveform 2 1.5 V 1.5 V 1.5 V Output S1 at GND VOL ≈ 0 V (see Note B) **VOLTAGE WAVEFORMS VOLTAGE WAVEFORMS PROPAGATION DELAY TIMES ENABLE AND DISABLE TIMES** INVERTING AND NONINVERTING OUTPUTS LOW- AND HIGH-LEVEL ENABLING

operating characteristics, $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}C$

PARAMETER

NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_Q = 50 Ω , t_f \leq 2.5 ns, t_f \leq 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpl 7 and tpH7 are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms



IMPORTANT NOTICE

Texas Instruments (TI) reserves the right to make changes to its products or to discontinue any semiconductor product or service without notice, and advises its customers to obtain the latest version of relevant information to verify, before placing orders, that the information being relied on is current.

TI warrants performance of its semiconductor products and related software to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are utilized to the extent TI deems necessary to support this warranty. Specific testing of all parameters of each device is not necessarily performed, except those mandated by government requirements.

Certain applications using semiconductor products may involve potential risks of death, personal injury, or severe property or environmental damage ("Critical Applications").

TI SEMICONDUCTOR PRODUCTS ARE NOT DESIGNED, INTENDED, AUTHORIZED, OR WARRANTED TO BE SUITABLE FOR USE IN LIFE-SUPPORT APPLICATIONS, DEVICES OR SYSTEMS OR OTHER CRITICAL APPLICATIONS.

Inclusion of TI products in such applications is understood to be fully at the risk of the customer. Use of TI products in such applications requires the written approval of an appropriate TI officer. Questions concerning potential risk applications should be directed to TI through a local SC sales office.

In order to minimize risks associated with the customer's applications, adequate design and operating safeguards should be provided by the customer to minimize inherent or procedural hazards.

TI assumes no liability for applications assistance, customer product design, software performance, or infringement of patents or services described herein. Nor does TI warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right of TI covering or relating to any combination, machine, or process in which such semiconductor products or services might be or are used.

Copyright © 1996, Texas Instruments Incorporated